

ABSTRACT OF THE DISCLOSURE

Provided is a radio wave absorbing thermally conductive sheet which has absorbency of noise radio wave and high thermal conductivity of absorbing generated heat and transfer it to an external system. The radio wave absorbing thermally conductive sheet 1 is capable of being attached between a semiconductor device such as CPU 2 and a heat sink 3 directly without aid of a member such as adhesives since its surface is adhesive. The sheet 1 comprises a soft sheet having a heat-resistant temperature over 150°C and a rubber hardness of 50 or less. Since the sheet is soft and is able to closely stick to at an attaching portion when implemented in an electronic circuit, absorbing performance of heat from a semiconductor device and an electromagnetic wave. Furthermore, since the sheet 1 is configured as containing 100 parts by weight of liquid silicon resin, 300 parts by weight of soft magnetic powder, and 100 parts by weight of nonmagnetic inorganic powder, high radio wave absorbing performance in particular from 100 MHz to a few GHz and excellent thermal conductivity are accomplished.